

In the Abstract

Delete the Abstract on page 26 and replace it with the following Abstract:

Methods of engaging an electronic module interconnected to a circuit board to a heat sink using clamping assemblies that maintain integrities of an interconnection grid array and the electronic module. A loading block having a plurality of legs is positioned at a backside of the module toward the circuit board in a location corresponding to a central area of the interconnection grid array. A spring having a central fastening means and plurality of peripheral securing means is positioned adjacent the loading block. The fastening means is actuated whereby central backside compressive forces are ~~direct~~directed at and force the loading block against the circuit board, while forces are applied to the securing means for engaging the securing means into the heat sink such that the electronic module is engaged with the heat sink. The clamping assembly relocates the regions of highest compression on the interconnection array, thereby maintaining the integrity thereof.